



COOLPad® CP1012

Interface pads



DescriptionCOOLPad® is a line of high performance thermal interface pads, developed to address the industry's growing requirements for easy application, low levels of thermal resistance and high conformability, even at the most challeging and uneven surfaces. COOLPad® is specially suitable for applications with low clamping forces between the heat generating component and the heat disspation surface.



Features

- Low Thermal Resistance
- High Conformability
- Electrically Insulating
- RoHS, REACH and compliant"



Applications

- Electronic components like LEDs, CPUs, MOS
- Mobiles, Laptops, Tablets
- **Electrical Vehicle Batteries**
- Power devices and modules"



Delivery FormatSheets of 200x400m

- Die-cut parts"



COOLPad® CP1012



Typical Properties

| Properties | Standard | Unit | CP1012 |
|----------------------------|------------|-----------|-----------------------|
| Color | - | - | Grey |
| Carrier Type | - | - | Silicon |
| Carrier Reinforcement | | | No |
| Thickness | ASTM D374 | mm (inch) | 0,25-5,0 (0,010-0,20) |
| Density | ASTM D792 | g/cm³ | 3,40 |
| Thermal Conductivity | ASTM D5470 | W/m.k | 12,00 |
| Volume Resistance | ASTM D257 | ohms.cm | 3.1*1011 |
| Thermal Resistance (50psi) | ASTM D5470 | °C-in2/W | 0,013 |
| Hardness | Shore C | - | 20,00 |
| Thermal Resistance | ASTM D5470 | °C | -60 to 200 |
| Dielectric Strength | ASTM D149 | kV/mm | > 5,0 |
| Shelf Life | - | - | 5 years |